

Abstract

Copper conductor tracks of circuit boards require a coating which has good corrosion resistance and is suitable for multiple solderability and bondability to enable them to be provided with electronic components. These properties are fulfilled by a layer system
5 which has an intermediate layer of autocatalytically deposited nickel on which a palladium layer has been deposited by charge exchange. To ensure reliable adhesive strength, low porosity and a good homogeneity, the bath for deposition of the palladium layer contains a copper compound. To passivate the palladium layer, the layer system can be provided with a final layer of gold deposited by charge exchange and/or
10 autocatalytically.